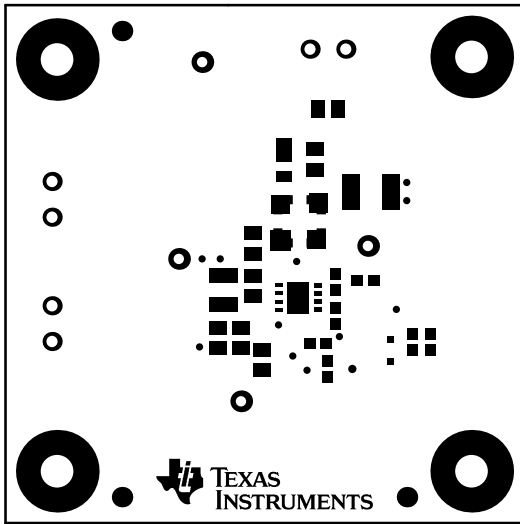
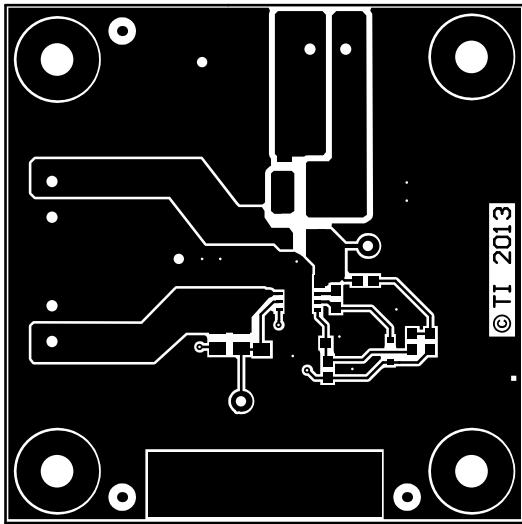


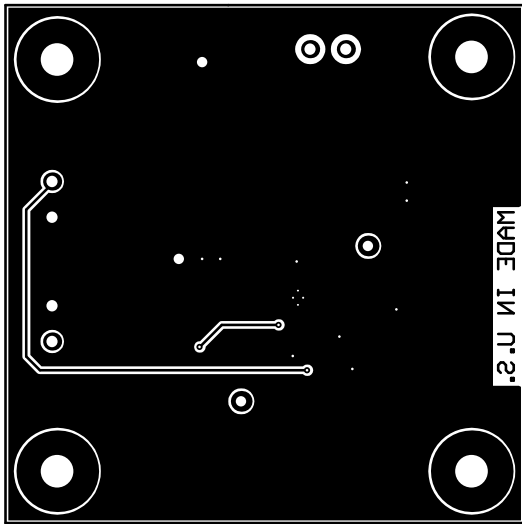
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 4/2/2015 12:01:39 PM	TEXAS INSTRUMENTS	



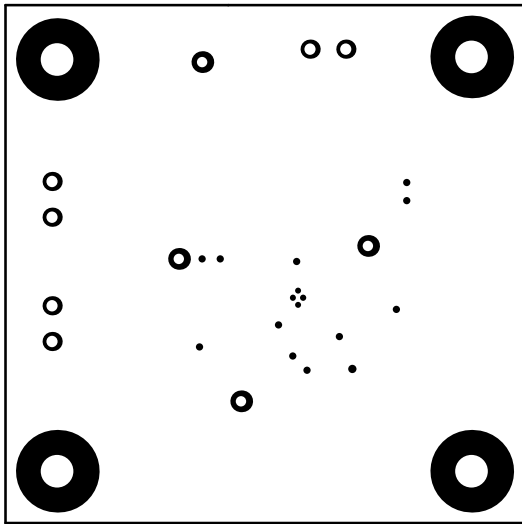
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 4/2/2015	12:01:40 PM	TEXAS INSTRUMENTS



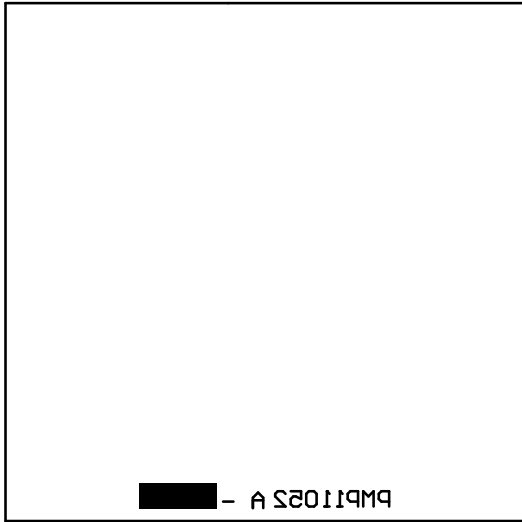
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LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 4/2/2015 12:01:41 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 4/2/2015 12:01:41 PM	TEXAS INSTRUMENTS	

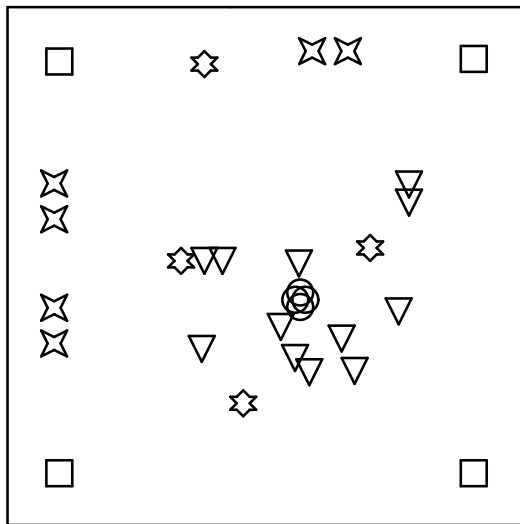


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 4/2/2015 12:01:42 PM	TEXAS INSTRUMENTS	

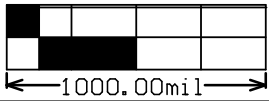
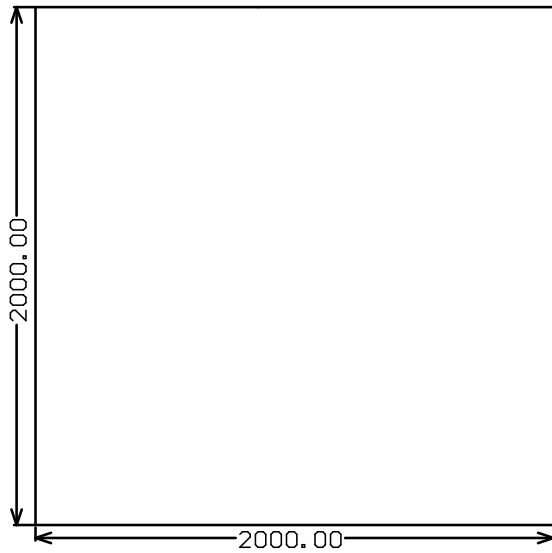


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 4/2/2015 12:01:42 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
○	4	7.87mil (0.200mm)	PTH	Round
▽	12	10.00mil (0.254mm)	PTH	Round
✱	4	40.00mil (1.016mm)	PTH	Round
✕	6	43.31mil (1.100mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
	30 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 4/2/2015 12:01:43 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11052	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 4/2/2015 12:01:44 PM	TEXAS INSTRUMENTS	

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